

Performance and Test Methods

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	Characteristic Value	Appearance	Test Conditions
Electrode Bending Strength	Z: Changing ratio within ±25% before / after the tests. Rdc: Value within the product requirement.		PCB Bending range=2.0mm PCB Thickness=0.8mm R=340 Bending Range Motherboard 45±2 45±2 Total Amplitude: 1.5mm
Vibration Proof			1 Cycle: 10 - 55 -10Hz/minute. To be measured after applying in each direction of x ,y and z for 2 hours under the above conditions.
Resistance to Soldering Heat			Preheating Temperature: 100 to150°C Preheating Duration: 1 min. Solder Temperature: 260±10°C Dipping Duration: 10±0.5 sec.
Solderability	90% or more of electrode surface wetted by new solder	No remarkable damages.	Preheating Temperature: 100 to150°C Preheating Duration: 1 min. Solder Temperature: 230±5°C Dipping Duration: 3±1 sec.
Temperature Cycle	Changing ratio within ±30% Rdc: Value within the product requirement		1 cycle means the repeating tests of 1 through 4 stages as shown in the table below. N = 125 cycle, No-load To be measured after being left at normal temperature and humidity for 2 to24 hours. Stage 1 2 3 4
			Temp. (°C) -55±3 +20±15 +125±3 +20±15
			Duration (min.) 30±3 15±5 30±3 15±5
Humidity Resistance			Temperature: +40°C±2°C, Relative Humidity: 90 to 95%RH Duration(hours) 500hrs±24hrs No-load To be measured after being left at normal temperature and humidity for 2 to24 hours.
Solvent Resistance			Reagent: Isopropyl alcohol (JIS K 8839) Temperature: 20°C ~25°C Dipping Duration: 30 sec.±5 sec.(without stirring) To be measured after being left at normal temperature and humidity for 2 to 24 hours.